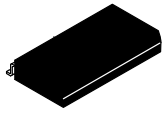
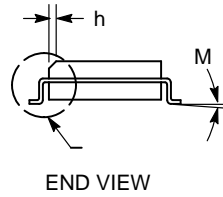
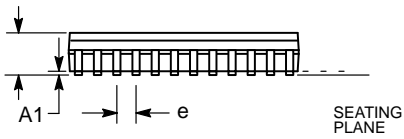
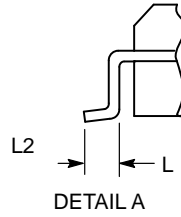
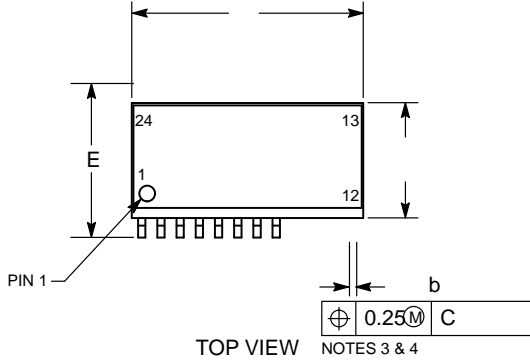


SOIC i24 WB LESS PIN 21
CASE 752AB i01
ISSUE O

DATE 17 AUG 2010



SCALE 1:1



DIM	MILLIMETERS	
	MIN	MAX
A	2.35	2.65

b	0.31	0.51
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e	1.27 BSC
h	0.25 0.75

- XXXXX = Specific Device Code
- A = Assembly Location
- WL = Wafer Lot
- YY = Year
- WW = Work Week
- G = Pb iFree Package